

SOT2204-1

FC-PBGA716, flip chip - plastic ball grid array, 716 terminals, 0.7 mm pitch, 19 mm x 19 mm x 2 mm body

24 April 2026

Package information



1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	FC-PBGA716
Package style descriptive code	FC-PBGA (flip chip - plastic ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	12-12-2025
Manufacturer package code	98ASA02037D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	18.9	19	19.1	mm
package width	18.9	19	19.1	mm
seated height	1.78	2	2.2	mm
nominal pitch	-	0.7	-	mm
actual quantity of termination	-	716	-	



FC-PBGA716, flip chip - plastic ball grid array, 716 terminals, 0.7 mm pitch, 19 mm x 19 mm x 2 mm body

2 Package outline

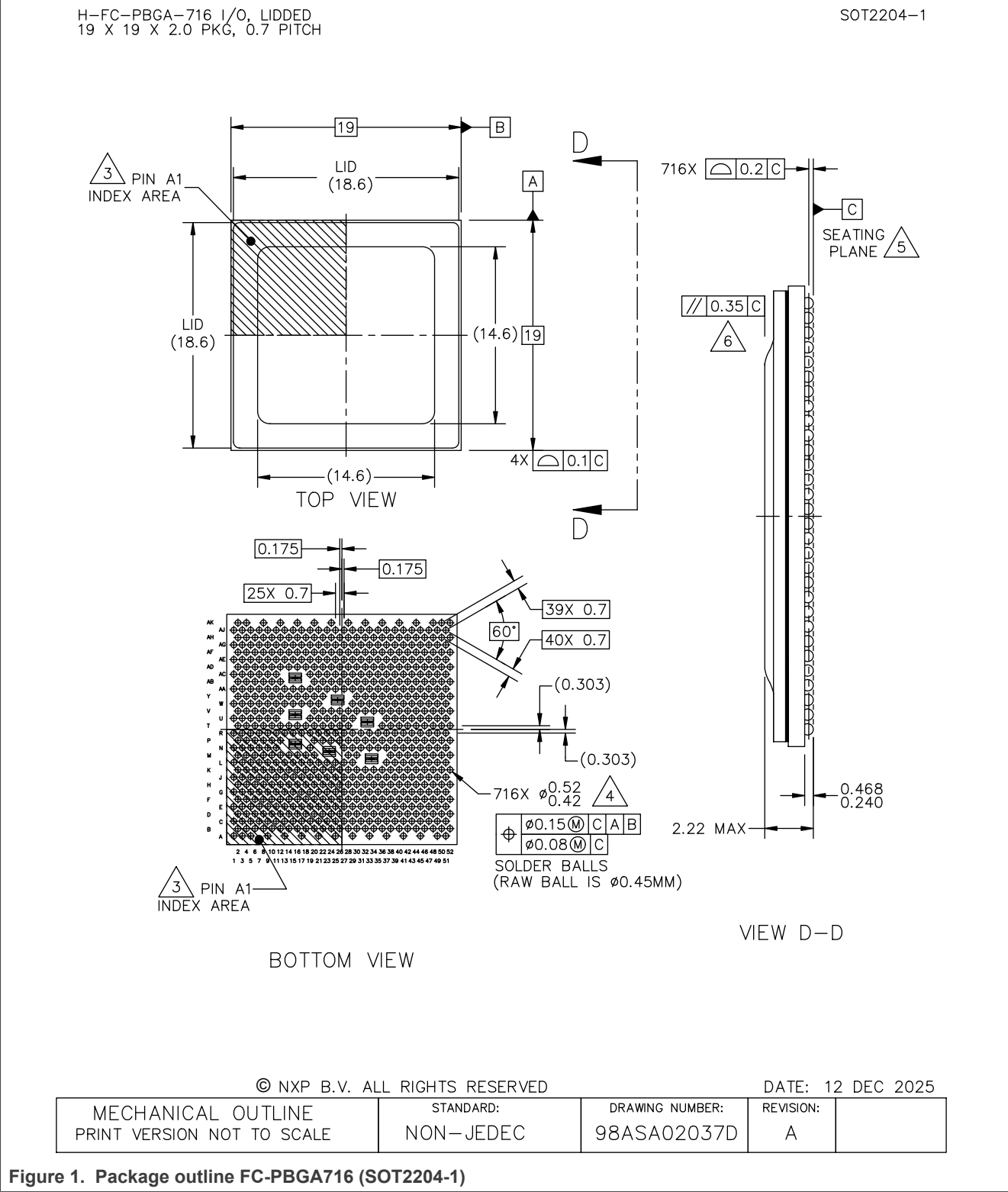
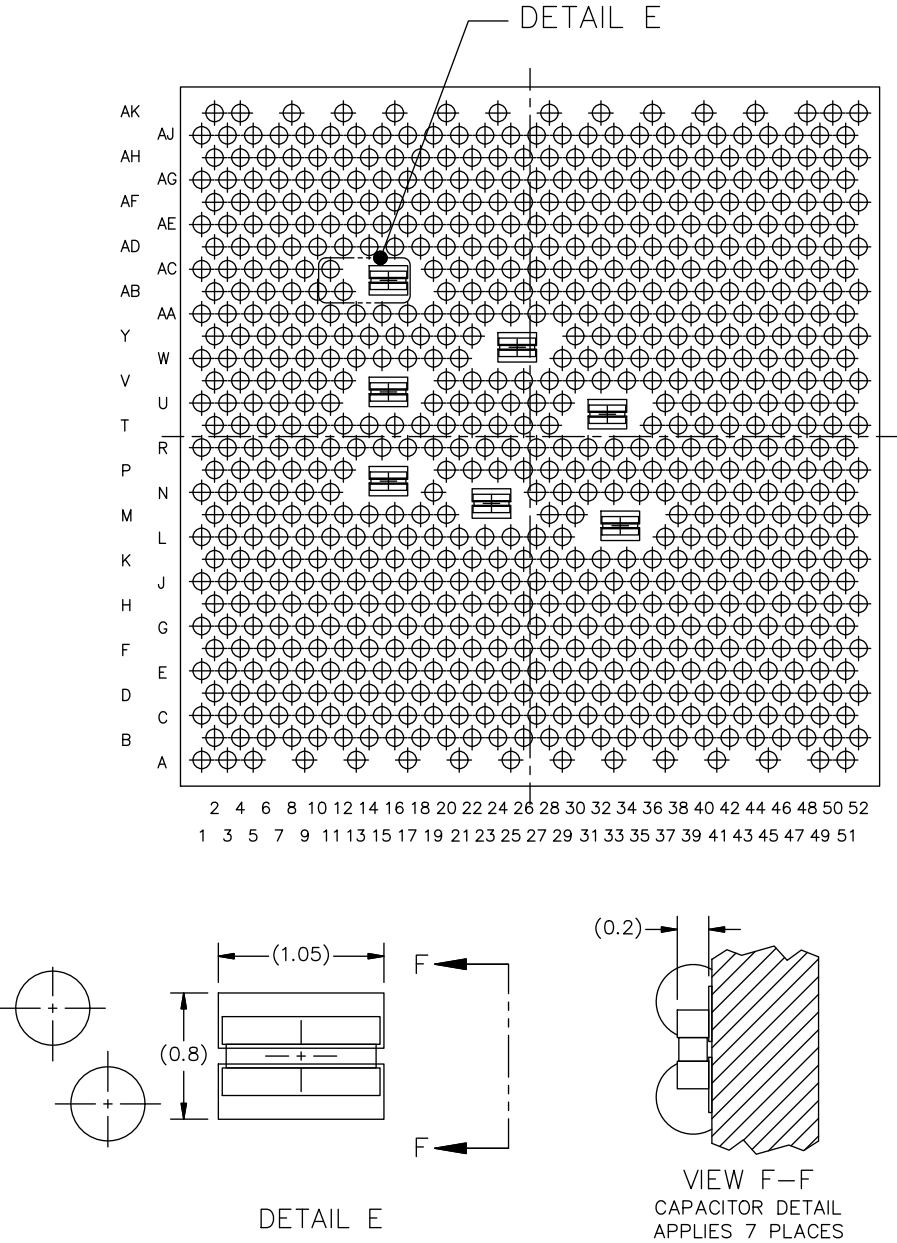


Figure 1. Package outline FC-PBGA716 (SOT2204-1)

FC-PBGA716, flip chip - plastic ball grid array, 716 terminals, 0.7 mm pitch, 19 mm x 19 mm x 2 mm body

H-FC-PBGA-716 I/O, LIDDED
19 X 19 X 2.0 PKG, 0.7 PITCH

SOT2204-1

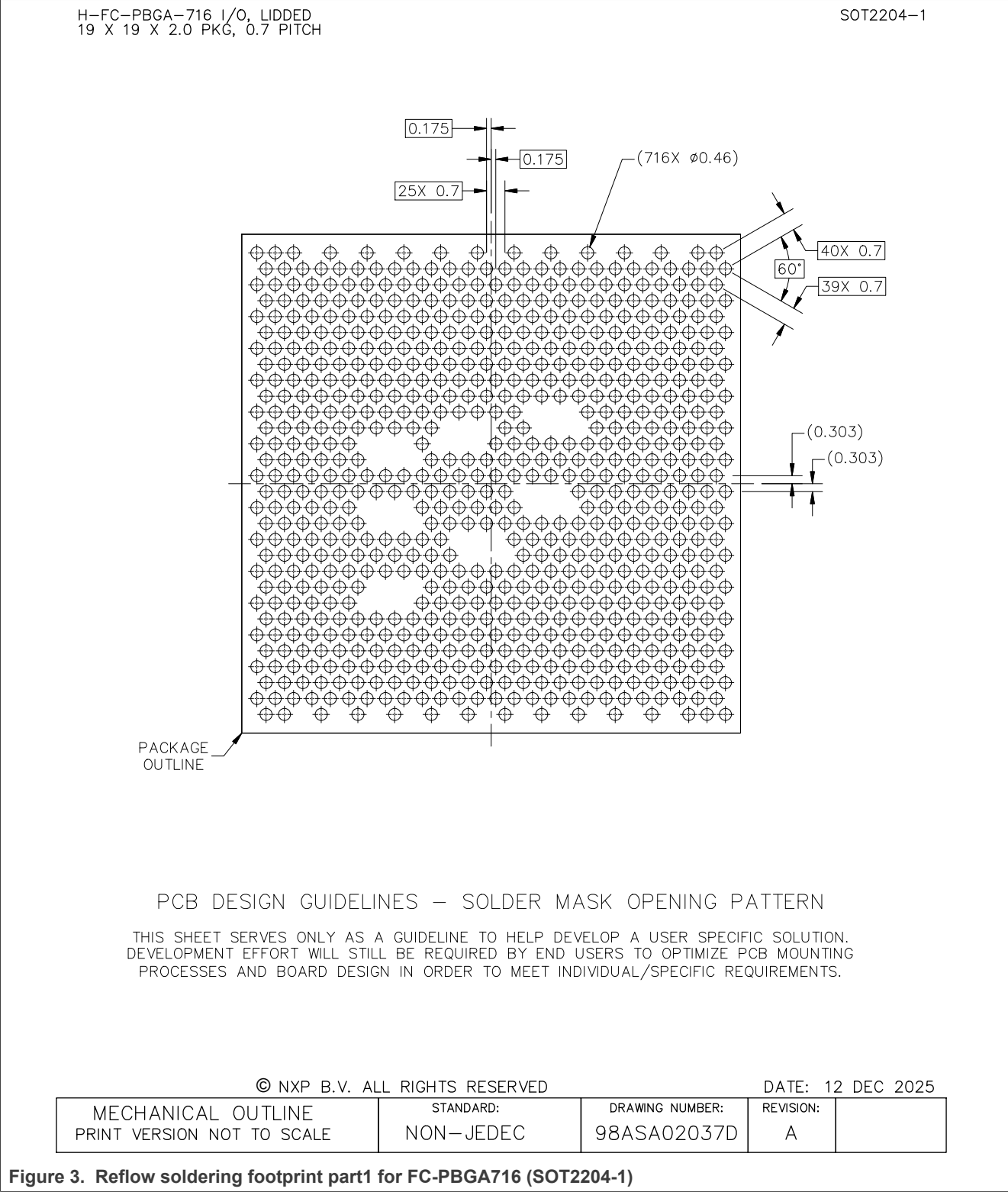


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Figure 2. Package outline detail E of FC-PBGA716 (SOT2204-1)

FC-PBGA716, flip chip - plastic ball grid array, 716 terminals, 0.7 mm pitch, 19 mm x 19 mm x 2 mm body

3 Soldering



FC-PBGA716, flip chip - plastic ball grid array, 716 terminals, 0.7 mm pitch, 19 mm x 19 mm x 2 mm body

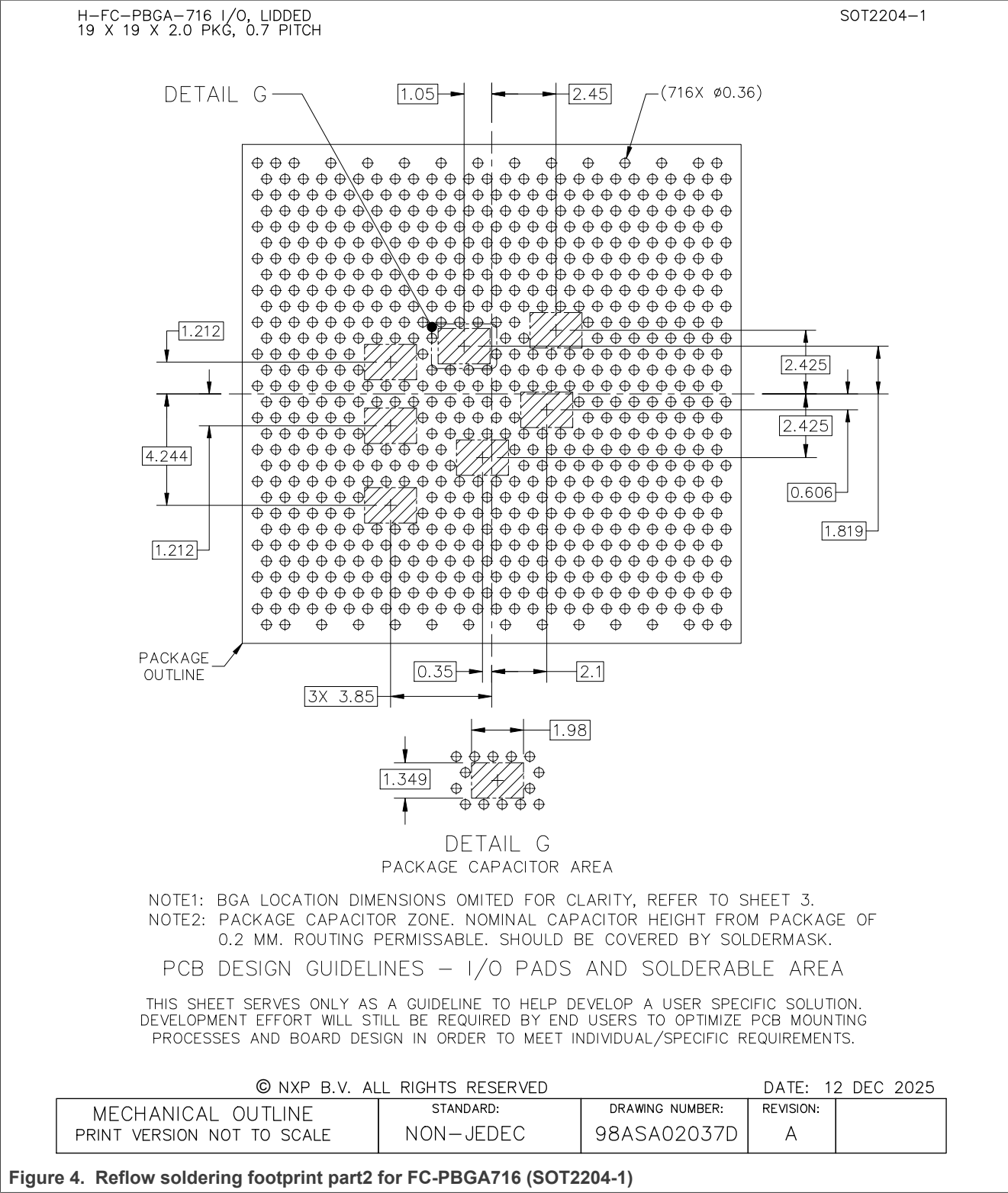
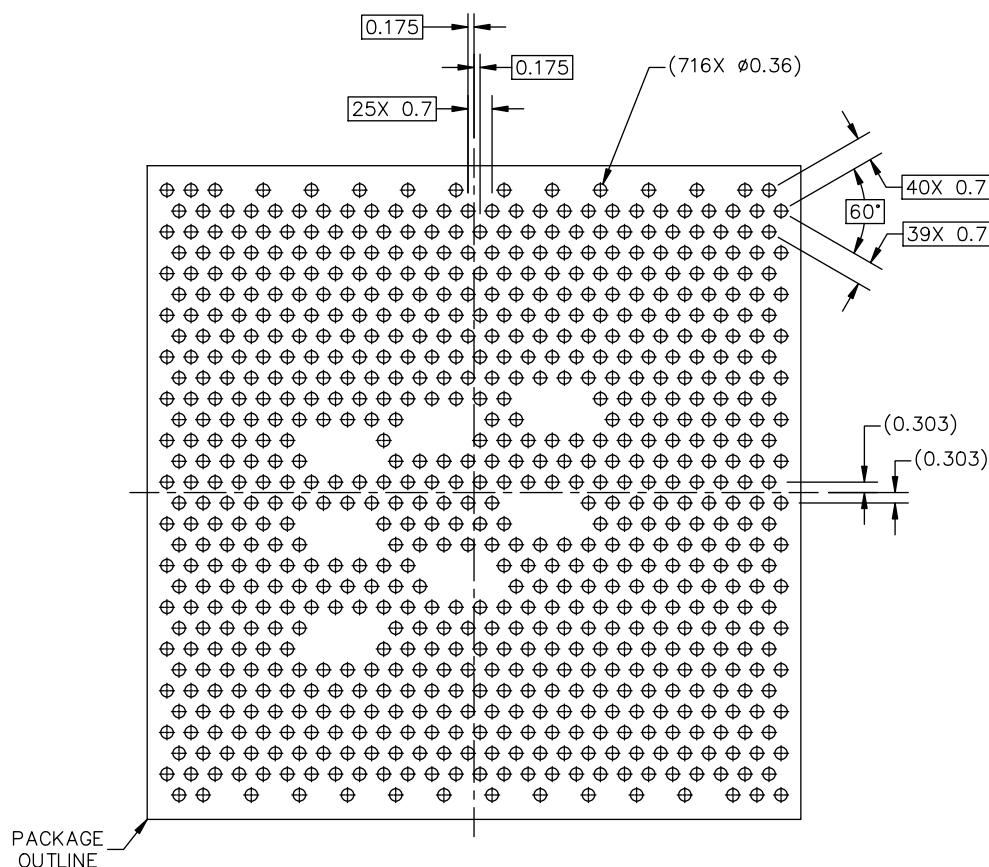


Figure 4. Reflow soldering footprint part2 for FC-PBGA716 (SOT2204-1)

FC-PBGA716, flip chip - plastic ball grid array, 716 terminals, 0.7 mm pitch, 19 mm x 19 mm x 2 mm body

H-FC-PBGA-716 I/O, LIDDED
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RECOMMENDED STENCIL THICKNESS 0.125 MM

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION.
DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING
PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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Figure 5. Reflow soldering footprint part3 for FC-PBGA716 (SOT2204-1)

FC-PBGA716, flip chip - plastic ball grid array, 716 terminals, 0.7 mm pitch, 19 mm x 19 mm x 2 mm body

H-FC-PBGA-716 I/O, LIDDED
19 X 19 X 2.0 PKG, 0.7 PITCH

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NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
- 4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
- 5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
- 7. LID OVERHANG ON SUBSTRATE NOT ALLOWED.
- 8. VENT AREA BETWEEN LID AND SUBSTRATE, SIZE MAY VARY.

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Figure 6. Package outline note FC-PBGA716 (SOT2204-1)

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body

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